



64Mbyte (16Mx36) FP Mode 4K Ref. 72pin-SIMM Design  
Part No. HMD16M32M8GH

## GENERAL DESCRIPTION

The HMD16M32M8GH is a 16M x 32bit dynamic RAM high-density memory module. The module consists of eight CMOS 16M x 4bit DRAMs in 32-pin SOJ or TSOP packages mounted on a 72-pin glass-epoxy substrate. A 0.1 or 0.22uF decoupling capacitor is mounted on the printed circuit board for each DRAM components. The module is a Single In-line Memory Module with edge connections and is intended for mounting in to 72-pin edge connector sockets. All module components may be powered from a single 5V DC power supply and all inputs and outputs are TTL-compatible.

## FEATURES

wPart Identification

HMD16M32M8GH

---4K Cycles/64ms Ref, Gold

w Access times : 50, 60ns

w High-density 64MByte design

w Single + 5V  $\pm$ 0.5V power supply

w JEDEC standard Pdpin & pinout

w TTL compatible inputs and outputs  
w/CAS-before-/RAS & Hidden Refresh capability

w/RAS-only refresh capability

wFast Page Mode Operation

## OPTIONS

w Timing

50ns access

-5

60ns access

-6

w Packages

72-pin SIMM

M

## MARKING

## PERFORMANCE RANGE

Speed	t <sub>RAC</sub>	t <sub>CAC</sub>	t <sub>RC</sub>
5	50ns	13ns	90ns
6	60ns	15ns	110ns

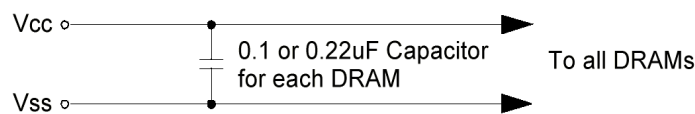
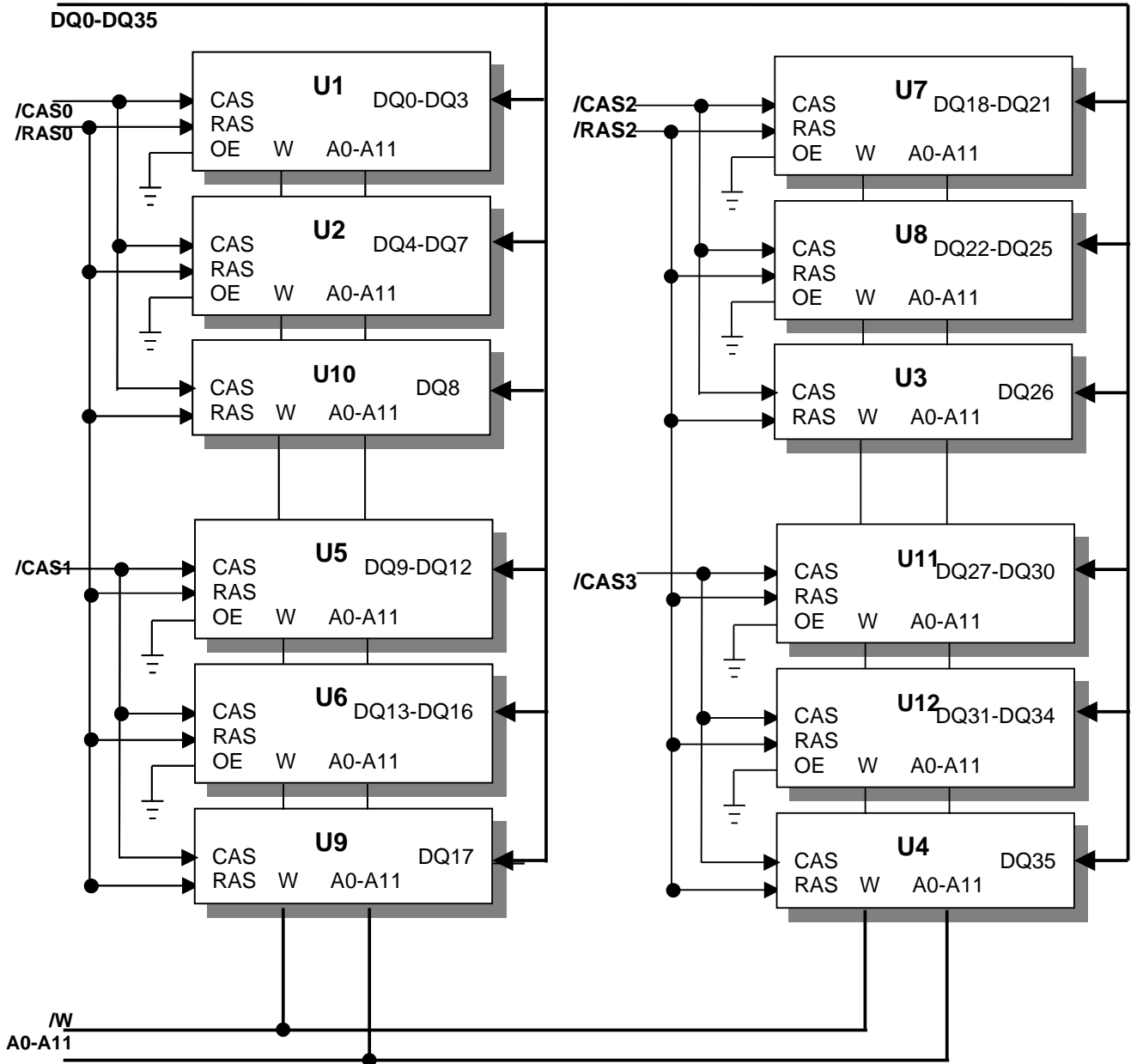
## PIN ASSIGNMENT

PIN	SYMBOL	PIN	SYMBOL	PIN	SYMBOL	PIN	SYMBOL
1	Vss	19	A10	37	NC	55	DQ12
2	DQ0	20	DQ4	38	NC	56	DQ30
3	DQ18	21	DQ22	39	Vss	57	DQ13
4	DQ1	22	DQ5	40	/CAS0	58	DQ31
5	DQ19	23	DQ23	41	/CAS2	59	Vcc
6	DQ2	24	DQ6	42	/CAS3	60	DQ32
7	DQ20	25	DQ24	43	/CAS1	61	DQ14
8	DQ3	26	DQ7	44	/RAS0	62	DQ33
9	DQ21	27	DQ25	45	NC	63	DQ15
10	Vcc	28	A7	46	NC	64	DQ34
11	NC	29	A11	47	/W	65	DQ16
12	A0	30	Vcc	48	NC	66	NC
13	A1	31	A8	49	DQ9	67	PD1
14	A2	32	A9	50	DQ27	68	PD2
15	A3	33	NC	51	DQ10	69	PD3
16	A4	34	/RAS2	52	DQ28	70	PD4
17	A5	35	NC	53	DQ11	71	NC
18	A6	36	NC	54	DQ29	72	Vss

## PRESENCE DETECT PINS

Pin	50ns	60ns
PD1	Vss	Vss
PD2	NC	NC
PD3	Vss	NC
PD4	Vss	NC

FUNCTIONAL BLOCK DIAGRAM



**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	RATING
Voltage on Any Pin Relative to Vss	$V_{IN\_OUT}$	-1V to 7.0V
Voltage on Vcc Supply Relative to Vss	Vcc	-1V to 7.0V
Power Dissipation	$P_D$	12W
Storage Temperature	$T_{STG}$	-55°C to 125°C
Short Circuit Output Current	$I_{OS}$	50mA

w Permanent device damage may occur if " Absolute Maximum Ratings" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**RECOMMENDED DC OPERATING CONDITIONS**

( Voltage reference to V<sub>SS</sub>, T<sub>A</sub>=0 to 70 ° C )

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT
Supply Voltage	Vcc	4.5	5.0	5.5	V
Ground	Vss	0	0	0	V
Input High Voltage	$V_{IH}$	2.4	-	Vcc	V
Input Low Voltage	$V_{IL}$	-1.0	-	0.8	V

**DC AND OPERATING CHARACTERISTICS**

SYMBOL	SPEED	MIN	MAX	UNITS
$I_{CC1}$	-5	-	1080	mA
	-6	-	960	mA
$I_{CC2}$	Don't care	-	24	mA
$I_{CC3}$	-5	-	1080	mA
	-6	-	960	mA
$I_{CC4}$	-5	-	840	mA
	-6	-	600	mA
$I_{CC5}$	Don't care	-	12	mA
$I_{CC6}$	-5	-	1080	mA
	-6	-	960	mA
$I_{I(L)}$	Don't care	-10	10	μA
$I_{O(L)}$		-5	5	μA
$V_{OH}$		2.4	-	V
$V_{OL}$		-	0.4	V

$I_{CC1}$  : Operating Current \* (/RAS , /CAS , Address cycling @t<sub>RC</sub>=min.)

$I_{CC2}$ : Standby Current ( /RAS=/CAS= $V_{IH}$  )

$I_{CC3}$ : /RAS Only Refresh Current \* ( /CAS= $V_{IH}$ , /RAS, Address cycling @ $t_{RC}=\min$  )

$I_{CC4}$ : Fast Page Mode Current \* ( /RAS= $V_{IL}$ , /CAS, Address cycling @ $t_{PC}=\min$  )

$I_{CC5}$ : Standby Current ( /RAS=/CAS= $V_{CC}-0.2V$  )

$I_{CC6}$ : /CAS-Before-/RAS Refresh Current \* ( /RAS and /CAS cycling @ $t_{RC}=\min$  )

$I_{IL}$ : Input Leakage Current (Any input  $0V \leq V_{IN} \leq 6.5V$ , all other pins not under test = 0V)

$I_{OL}$ : Output Leakage Current (Data out is disabled,  $0V \leq V_{OUT} \leq 5.5V$ )

$V_{OH}$ : Output High Voltage Level ( $I_{OH} = -5mA$ )

$V_{OL}$ : Output Low Voltage Level ( $I_{OL} = 4.2mA$ )

\* **NOTE:**  $I_{CC1}$ ,  $I_{CC3}$ ,  $I_{CC4}$  and  $I_{CC6}$  are dependent on output loading and cycle rates. Specified values are obtained with the output open.  $I_{CC}$  is specified as an average current. In  $I_{CC1}$  and  $I_{CC3}$ , address can be changed maximum once while /RAS= $V_{IL}$ . In  $I_{CC4}$ , address can be changed maximum once within one page mode cycle.

## CAPACITANCE ( $T_A=25^\circ C$ , $V_{CC} = 5V$ , $f = 1MHz$ )

DESCRIPTION	SYMBOL	MIN	MAX	UNITS
Input Capacitance (A0-A11)	$C_{IN1}$	-	50	pF
Input Capacitance (/W)	$C_{IN2}$	-	66	pF
Input Capacitance (/RAS0)	$C_{IN3}$	-	38	pF
Input Capacitance (/CAS0-/CAS3)	$C_{IN4}$	-	24	pF
Input/Output Capacitance (DQ0-31)	$C_{DQ1}$	-	17	pF

## AC CHARACTERISTICS ( $0^\circ C \leq T_A \leq 70^\circ C$ , $V_{CC} = 5V \pm 10\%$ , See notes 1,2.)

PARAMETER	SYMBOL	-5		-6		UNIT
		MIN	MAX	MIN	MAX	
Random read or write cycle time	$t_{RC}$	84		104		ns
Access time from /RAS	$t_{RAC}$		50		60	ns
Access time from /CAS	$t_{CAC}$		13		15	ns
Access time from column address	$t_{AA}$		25		30	ns
/CAS to output in Low-Z	$t_{CLZ}$	3		3		ns
Output buffer turn-off delay	$t_{OFF}$	3	13	3	15	ns
Transition time (rise and fall)	$t_T$	1	50	1	50	ns
/RAS precharge time	$t_{RP}$	30		40		ns
/RAS pulse width	$t_{RAS}$	50	10K	60	10K	ns
/RAS hold time	$t_{RSH}$	13		15		ns
/CAS hold time	$t_{CSH}$	38		45		ns
/CAS pulse width	$t_{CAS}$	8	10K	10	10K	ns
/RAS to /CAS delay time	$t_{RCD}$	20	37	20	45	ns

/RAS to column address delay time	$t_{RAD}$	15	25	15	30	ns
/CAS to /RAS precharge time	$t_{CRP}$	5		5		ns
Row address set-up time	$t_{ASR}$	0		0		ns
Row address hold time	$t_{RAH}$	10		10		ns
Column address set-up time	$t_{ASC}$	0		0		ns
Column address hold time	$t_{CAH}$	8		10		ns
Column address hold referenced to /RAS	$t_{AR}$	50		55		ns
Column Address to /RAS lead time	$t_{RAL}$	25		30		ns
Read command set-up time	$t_{RCS}$	0		0		ns
Read command hold referenced to /CAS	$t_{RCH}$	0		0		ns
Read command hold referenced to /RAS	$t_{RRH}$	0		0		ns
Write command hold time	$t_{WCH}$	10		10		ns
Write command hold referenced to /RAS	$t_{WCR}$	50		55		ns
Write command pulse width	$t_{WCP}$	10		10		ns
Write command to /RAS lead time	$t_{RWL}$	13		10		ns
Write command to /CAS lead time	$t_{CWL}$	8		10		ns
Data-in set-up time	$t_{DS}$	0		0		ns
Data-in hold time	$t_{DH}$	8		10		ns
Data-in hold referenced to /RAS	$t_{DHR}$	50		55		ns
Refresh period	$t_{REF}$		64		64	ns
Write command set-up time	$t_{WCS}$	0		0		ns
/CAS setup time (C-B-R refresh)	$t_{CSR}$	5		5		ns
/CAS hold time (C-B-R refresh)	$t_{CHR}$	10		10		ns
/RAS precharge to /CAS hold time	$t_{RPC}$	5		5		ns
Access time from /CAS precharge	$t_{CPA}$		28		35	ns
Fast page mode cycle time	$t_{PC}$	40		45		ns
/CAS precharge time (Fast page)	$t_{CP}$	8		10		ns
/RAS pulse width (Fast page )	$t_{RASP}$	50	200K	60	200K	ns
/W to /RAS precharge time(C-B-R refresh)	$t_{WRP}$	10		10		ns
/W to /RAS hold time (C-B-R refresh)	$t_{WRH}$	10		10		ns
/CAS precharge(C-B-R counter test)	$t_{CPT}$	20		30		ns

**NOTES**

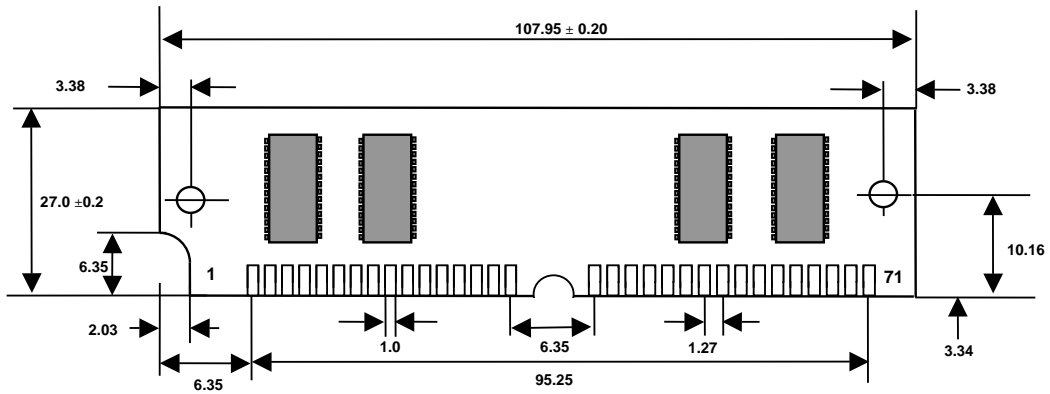
1. An initial pause of 200 $\mu$ s is required after power-up followed by any 8 /RAS-only or /CAS-before-/RAS refresh cycles before proper device operation is achieved.
2.  $V_{IH(min)}$  and  $V_{IL(max)}$  are reference levels for measuring timing of input signals. Transition times are measured between  $V_{IH(min)}$  and  $V_{IL(max)}$  and are assumed to be 5ns for all inputs.
3. Measured with a load equivalent to 2TTL loads and 100pF
4. Operation within the  $t_{RCD(max)}$  limit insures that  $t_{RAC(max)}$  can be met.  $t_{RCD(max)}$  is specified as a reference point only. If  $t_{RCD}$  is greater than the specified  $t_{RCD(max)}$  limit, then access time is controlled exclusively by  $t_{CAC}$ .

5. Assumes that  $t_{RCD} \geq t_{RCD(max)}$
6.  $t_{AR}$ ,  $t_{WCR}$ ,  $t_{DHR}$  are referenced to  $t_{RAD(max)}$
7. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to  $V_{OH}$  or  $V_{OL}$ .
8.  $t_{WCS}$ ,  $t_{RWD}$ ,  $t_{CWD}$  and  $t_{AWD}$  are non restrictive operating parameter.  
They are included in the data sheet as electrical characteristic only. If  $t_{WCS} \geq t_{WCS(min)}$  the cycle is an early write cycle and the data out pin will remain high impedance for the duration of the cycle.
9. Either  $t_{RCH}$  or  $t_{RRH}$  must be satisfied for a read cycle.
10. These parameters are referenced to the  $/CAS$  leading edge in early write cycles and to the  $/W$  leading edge in read-write cycles.
11. Operation within the  $t_{RAD(max)}$  limit insures that  $t_{RAC(max)}$  can be met.  $t_{RAD(max)}$  is specified as a reference point only. If  $t_{RAD}$  is greater than the specified  $t_{RAD(max)}$  limit, then access time is controlled by  $t_{AA}$ .

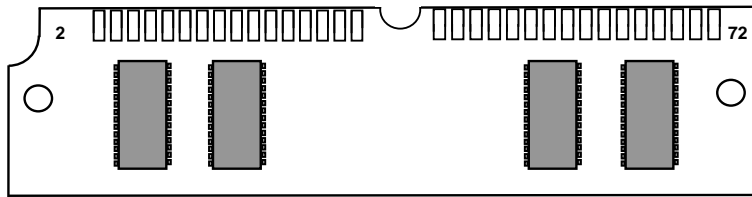
PACKAGING INFORMATION

SIMM Design

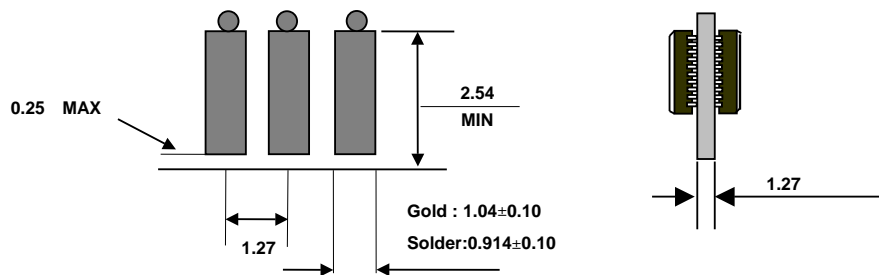
Unit : mm



Front View



Back View



ORDERING INFORMATION

Part Number	Density	Org.	Package	Ref.	Vcc	MODE	SPEED
HMD16M32M8GH-5	64Byte	x 32	72 Pin-SIMM-Gold	4K	5V	FPM	50ns
HMD16M32M8GH-6	64Byte	x 32	72 Pin-SIMM-Gold	4K	5V	FPM	60ns